

Customer No.: 31561
Application No.: 10/605,602
Docket No.: 10233-US-PA

AMENDMENTS

In the Claims:

Please amend the claims according to the following listing of claims and substitute it for all prior versions and listings of claims in the application.

1. (currently amended) A method of bonding a heat sink to a chip package structure, wherein the chip package structure at least comprises a chip and a stiffener ring around the chip with the stiffener ring set up over a substrate, and the heat sink comprises a first protruding section located at a position corresponding to the chip and a plurality of second protruding sections located at positions corresponding to the stiffener ring, the method comprising the steps of:

~~forming a gluing layer over the first protruding section and the second protruding sections of the heat sink;~~

providing a gluing tape, wherein the gluing tape comprises a cutting pattern with a shape that matches with the first protruding section and the second protruding sections of the heat sink;

aligning the first protruding section and the second protruding section of the heat sink with the cutting pattern and disposing the heat sink onto the gluing tape;

detaching the heat sink from the gluing tape so that a portion of the gluing tape remains adhered to the first and the second protruding sections to form the gluing layer; and

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bonding the heat sink to the chip package structure such that the first protruding section of the heat sink is attached to the chip and the second protruding sections of the heat sink are attached to the stiffener ring.

Claim 2 (cancelled)

3. (currently amended) The method of claim 21, wherein the gluing tape comprises a heat-softening double-sided adhesive tape.

4. (currently amended) The method of claim 21, wherein the gluing tape comprises a partially polymerized B-stage adhesive film.

5. (original) The method of claim 1, wherein a material constituting the heat sink comprises copper.

6. (original) The method of claim 1, wherein the first protruding section and the second protruding sections are formed together with the heat sink into an integral unit.

7. (original) The method of claim 1, wherein the sum area of all the second protruding sections is less than the area of the stiffener ring.

8. (original) The method of claim 1, wherein the step of bonding the heat sink to the chip package structure further comprises performing a curing operation.